

STM32G0-SO8-DISCO

MB1454

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U_MB1454_Top
MB1454_Top.SchDoc

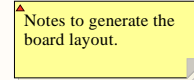


Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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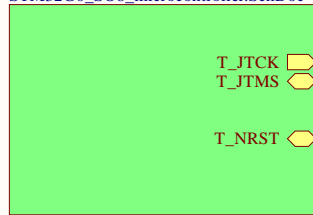
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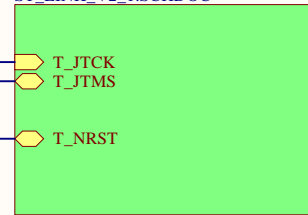
Title: Project overview	
Project: STM32G0-SO8-DISCO	
Variant: G031J6	
Revision: B-02	Reference: MB1454
Size: A4	Date: 1903/2019
Sheet: 1 of 5	



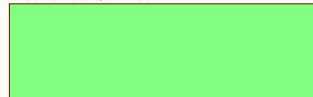
U_STM32G0_SO8_microcontroller
STM32G0_SO8_microcontroller.SchDoc



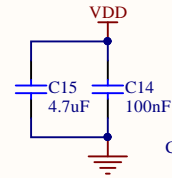
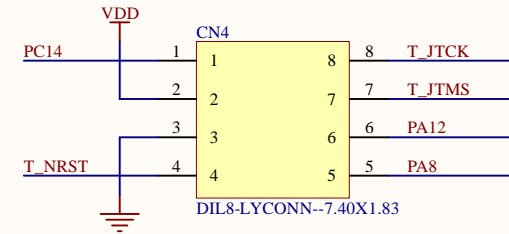
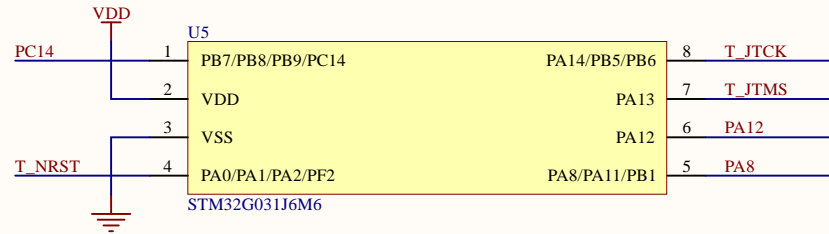
U_ST_LINK_V2_1
ST_LINK_V2_1.SCHDOC



Mechanical
Mechanical.SchDoc



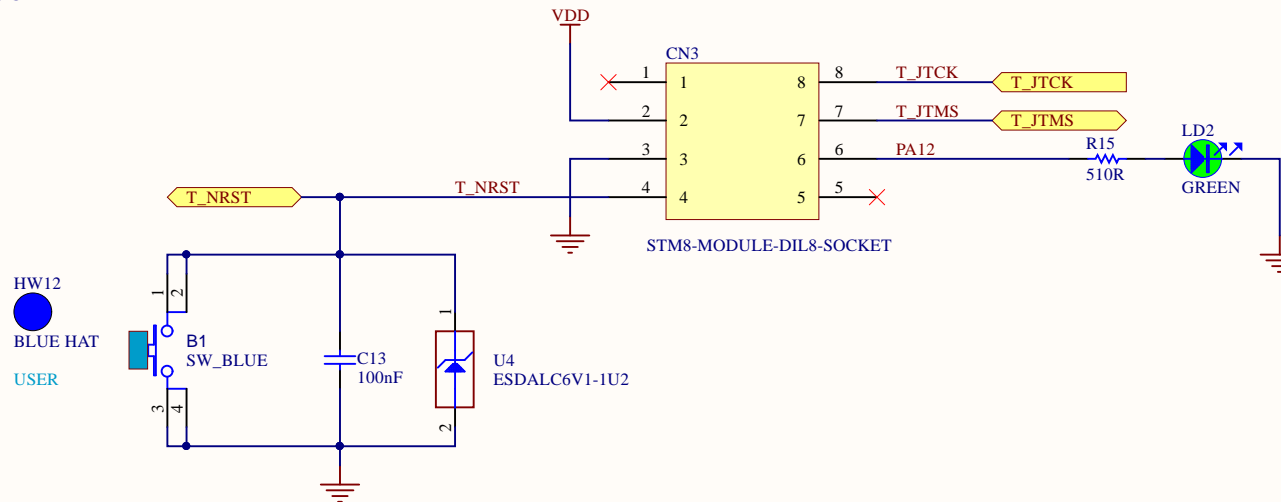
STM32G031Jx BREAKABLE MODULE



▲ Decoupling capacitors have to be as close as possible from the pins.

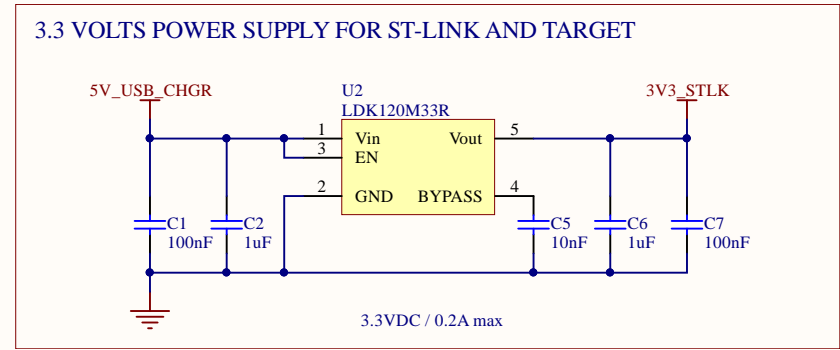
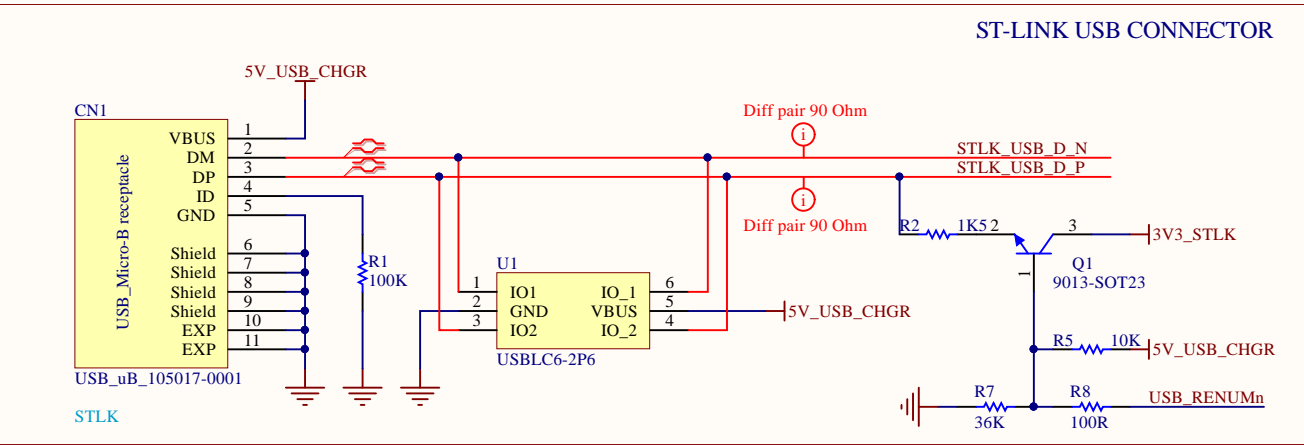
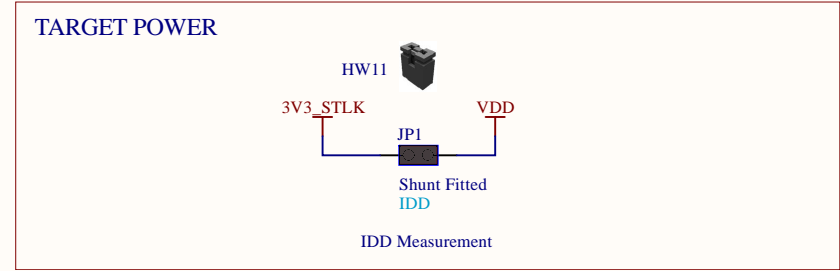
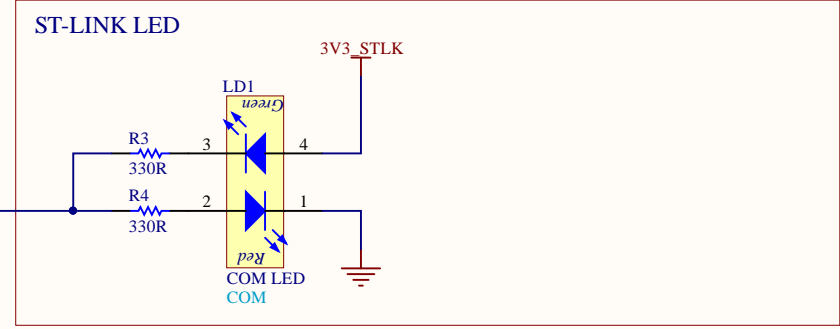
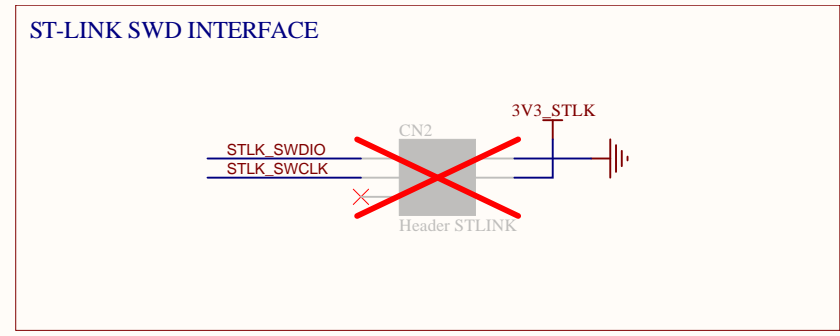
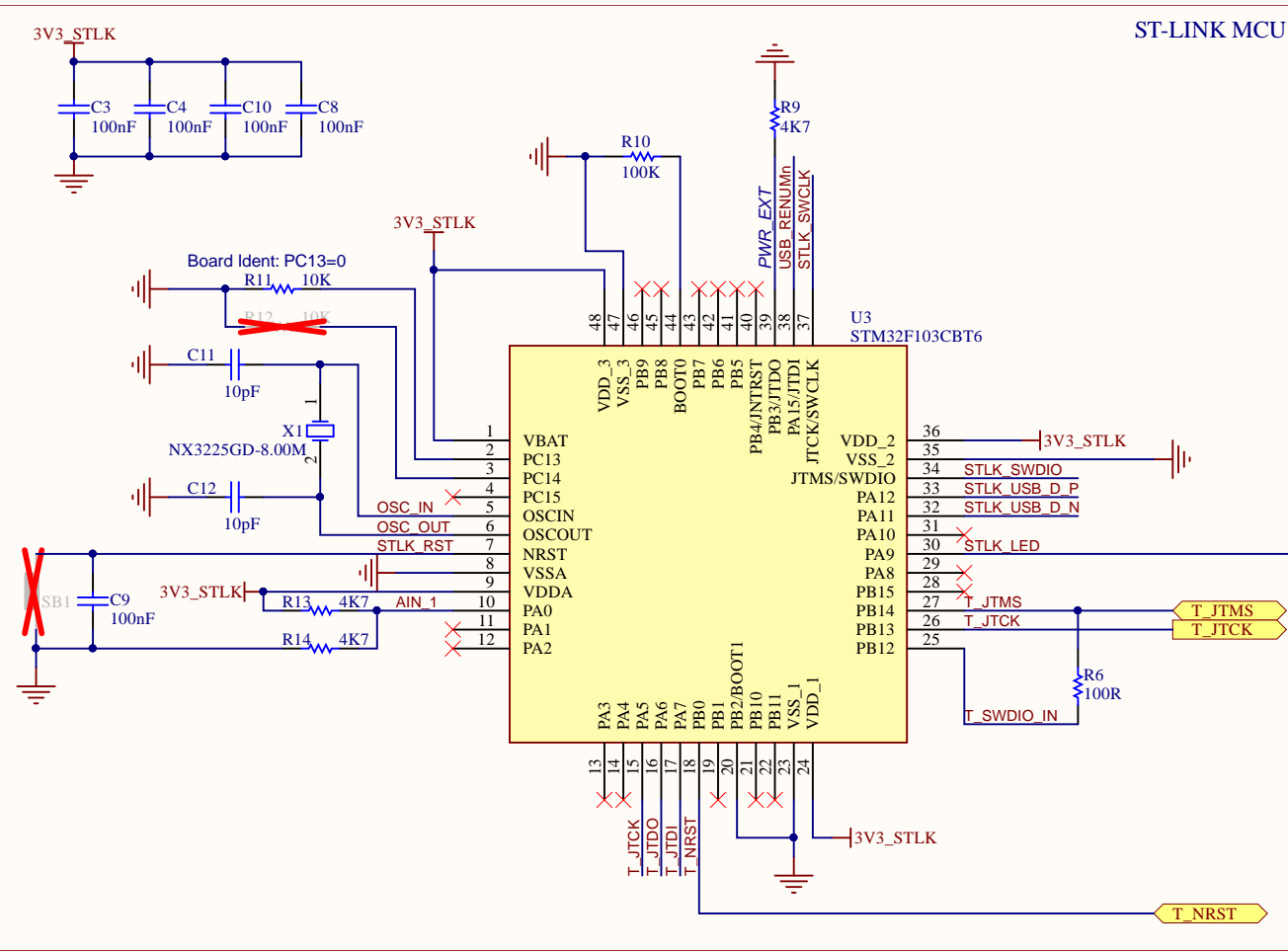
Ceramic capacitor (Low ESR, ESR<1ohm)

DIL8 SOCKET



GROUND TESTPOINT





HW4

BOARD REF

MB1454B-02 syywwxxxxx

HW3

BOARD CPN

STM32G0-S08-DISCO

HW100

PCB

MB1454B

HW1

LOGO ST

HW5

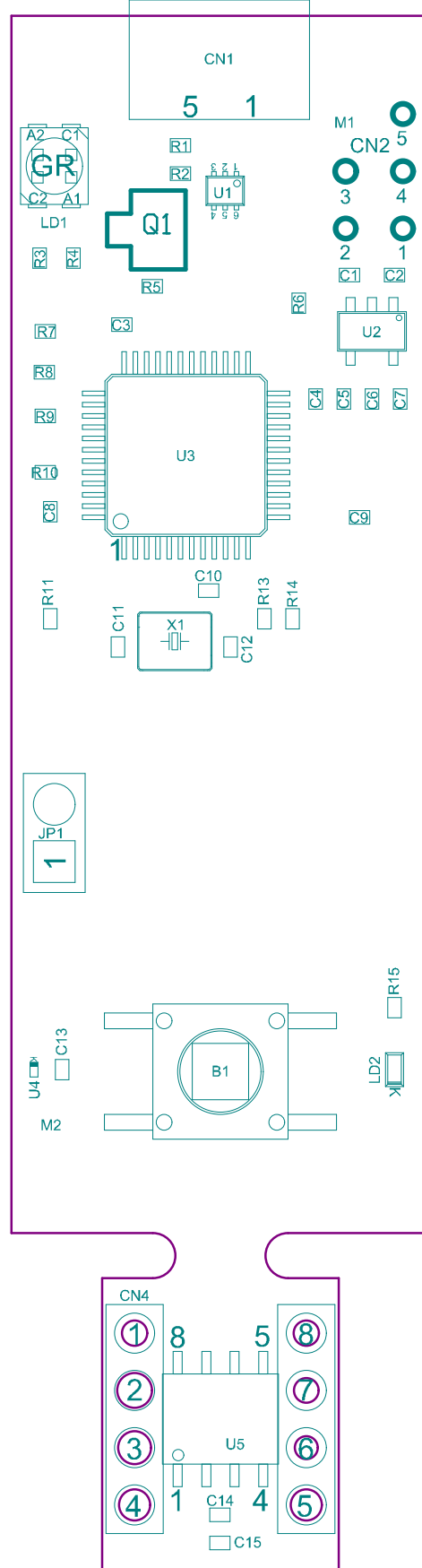
LOGO CE

HW2

LOGO ESD

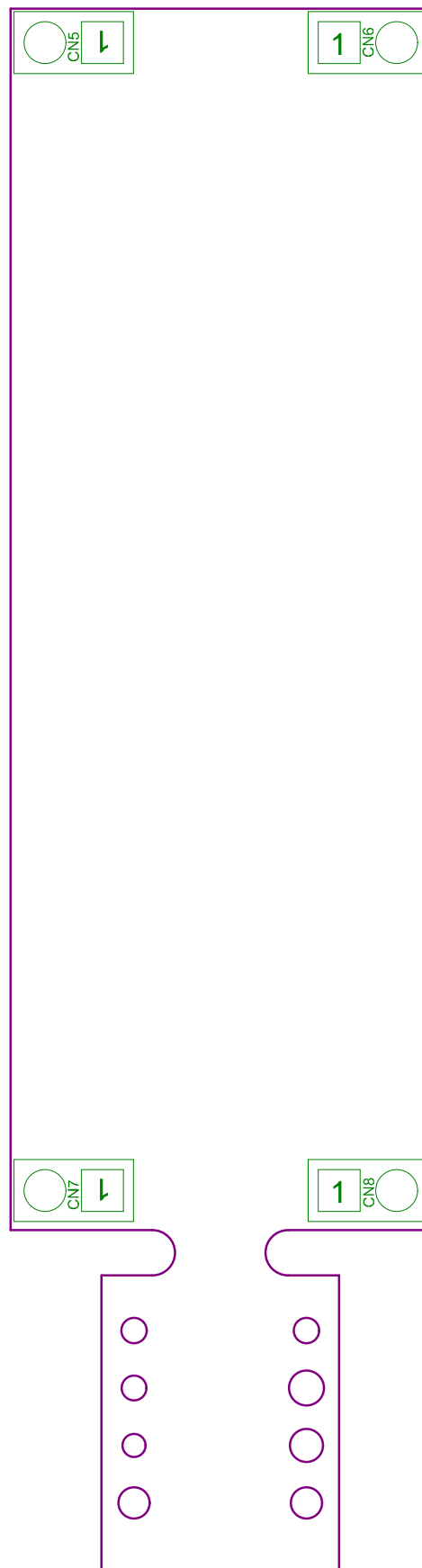
HW6

LOGO ROHS



Project: STM32G0-SO8-DISCO	
Layer: M14-Top Assembly	Gerber: .GM14
Variant: G031J6	Ref: MB1454
Date: 1903/2019	Rev: B





Project: STM32G0-SO8-DISCO	
Layer: M15-Bottom Assembly	Gerber: .GM15
Variant: G031J6	Ref: MB1454
Date: 1903/2019	Rev: B



